

### Fixed Attenuator Chip

- ◆ DC to 26.5 GHz
- ◆ 3 dB
- ◆ 200mW

#### Features

- Thin film
- High attenuation accuracy
- Small VSWR
- Ceramic chip: 99% alumina
- Laser trimmed
- Low cost-high performance

#### Model No. Description

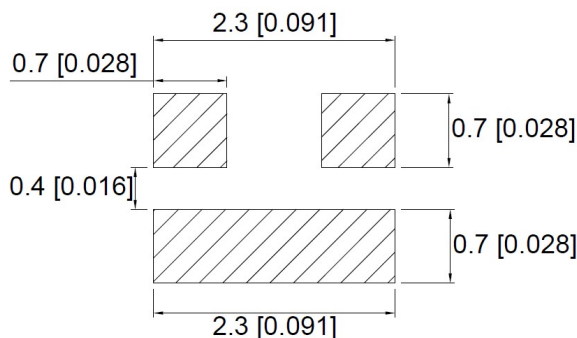
FACXXXXX

- X- Soldering method A or B
- XX- attenuation: \*\*dB.
- XX- frequency range 06: DC to 6GHz
  - 10: DC to 10GHz
  - 12: DC to 12.4GHz
  - 18: DC to 18GHz
  - 26: DC to 26.5GHz.

Soldering method A: The gold terminals in this Series are just designed to use wire-boning application.

Soldering method B: The gold terminals in this Series are just designed to use lead free reflow application.

#### Recommended Layout



#### Specifications

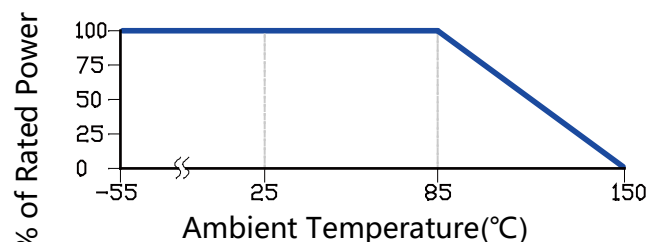
Frequency Range	DC to 26.5 GHz
Attenuation	3 dB
Attenuation Accuracy (Typical.)	±0.5 dB DC to 8.5 GHz + 0.5 dB 8.5 to 12.4 GHz + 0.5 dB 12.4 to 18 GHz + 1.0 dB 18 to 26.5 GHz
Attenuation Stability	0.0001 dB/dB/°C
Nominal Impedance	50 Ohm
Rated Input Power	200mW
Operating Temperature	-55 °C to +150 °C

FREQ. RANGE (GHz)	VSWR(:1) Typical
DC to 8.5	1.05
8.5 to 12.4	1.10
12.4 to 18	1.15
18 to 26.5	1.40

#### Material Specification

substrate	99% alumina
terminal	Gold over Tiw Gold thickness : 3 μ m
resistor	Tantalum nitride thin film

#### Average Power Derating Curve

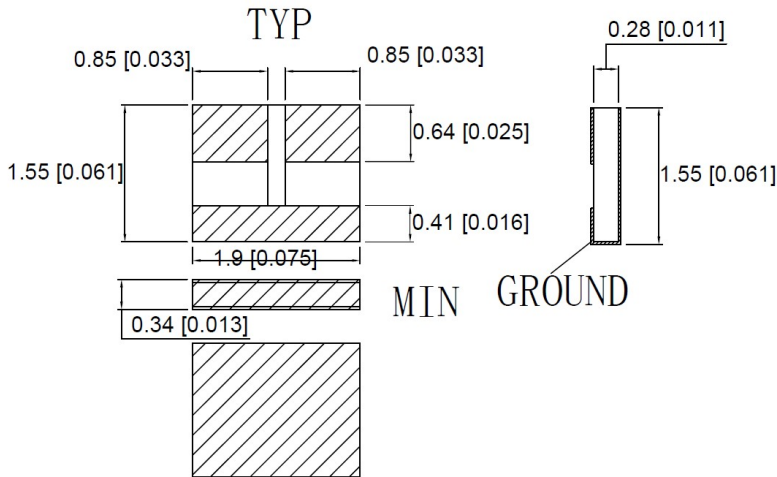


#### Yantel Corporation

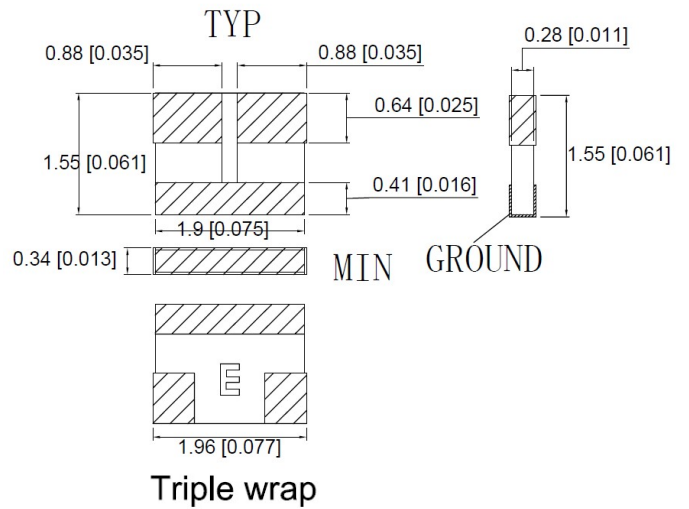
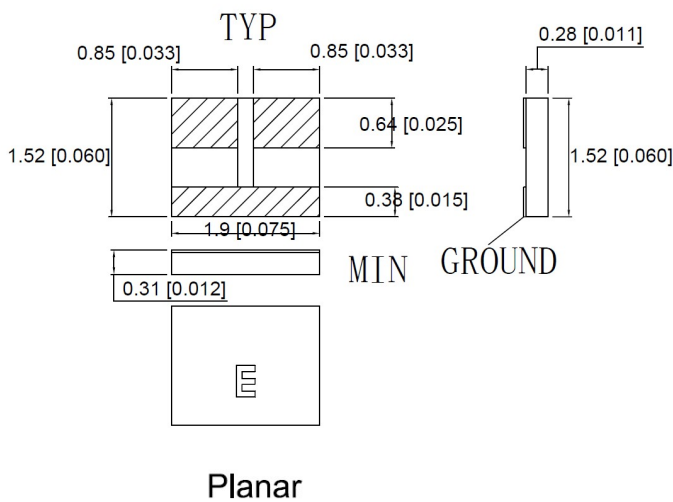
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**Package Outlines**

A: for wire-bonding



B: for lead free reflow (no code represents Planar, W3 represents Triple wrap)



Note: all dimensions shown in mm[inch]